



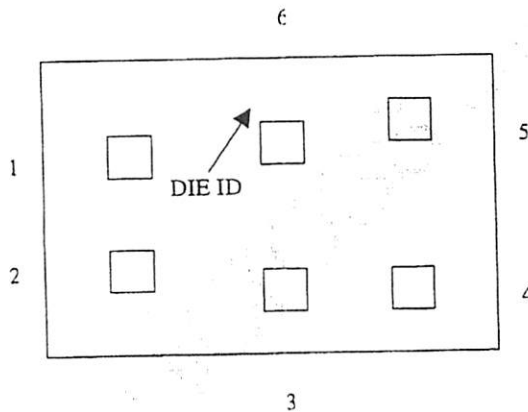
# Sierra Components, Inc.

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Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

### PAD FUNCTIONS

1. IN 1
2. IN 2
3. Vcc
4. Y
5. IN 0
6. GND



**Top Material: Al**  
**Backside Material: Silicon Nitride**  
**Bond Pad Size: .004" X .004"**  
**Backside Potential: Grnd (Or Leave Floating)**  
**Mask Ref:**

**APPROVED BY: DK**

**DIE SIZE .019" X .026"**

**DATE: 3/30/12**

**MFG: Texas Inst.**

**THICKNESS .025"**

**P/N: 54LVC1G98**